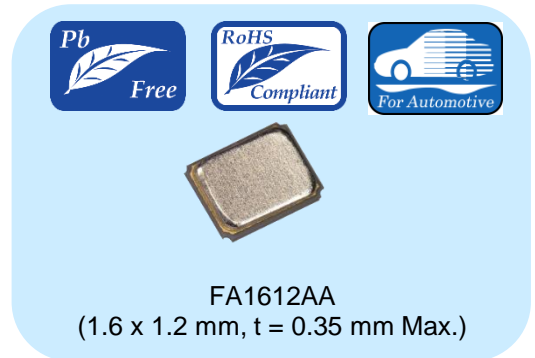


AEC-Q200 compliant small and high frequency MHz crystal unit:
Product Name: FA1612AA

Features

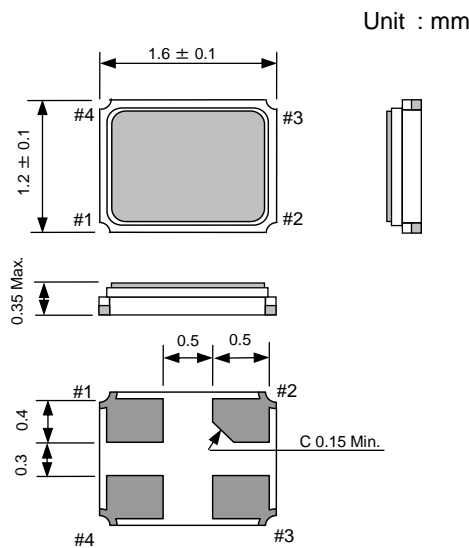
- AEC-Q200 Compliant
- Package size: 1.6 x 1.2 mm, t = 0.35 mm Max.
- Frequency range: 24 MHz to 80 MHz
- Frequency tolerance: $\pm 10 \times 10^{-6}$ (@+25 °C)
- Frequency vs. temperature characteristics:
 - $\pm 20 \times 10^{-6}$ (-40 °C to +85 °C)
 - $\pm 25 \times 10^{-6}$ (-40 °C to +105 °C)
 - $\pm 50 \times 10^{-6}$ (-40 °C to +125 °C)



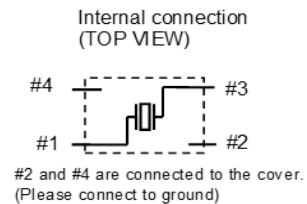
Description

With the evolution of in-vehicle devices such as electronic keys (key fobs), cameras, and TCUs (Telematics Control Units), there is a growing market need for miniaturization and modularization. In conjunction with this, customers are demanding small, thin, high-frequency crystal units. We have commercialized the FA1612AA to accommodate evolving wireless communication, AD (Autonomous Driving) and ADAS (Advanced Driver-Assistance Systems) technologies.

External Dimensions



Pin	Connection
#1	X'tal
#2	GND
#3	X'tal
#4	GND



[1] Product Number / Product Name

(1-1) Product Number

X1E000461xxxx26 (Please contact Epson for details)

(1-2) Product Name (Standard Form)

FA1612AA	55.200000MHz	12.0	+10.0-10.0
a	b	c	d

a: Model b: Frequency c: Load capacitance(pF) d: Frequency tolerance($\times 10^{-6}$, +25 °C)

In addition to the mentioned above specification items("a" to "d"),

and please specify the frequency vs. temperature characteristics (one of "e" to "g" specification below).

e: $\pm 20 \times 10^{-6}$ / -40 °C to +85 °C, f: $\pm 25 \times 10^{-6}$ / -40 °C to +105 °C, g: $\pm 50 \times 10^{-6}$ / -40 °C to +125 °C

[2] Absolute Maximum Ratings

Item	Symbol	Rating value			Unit	Note
		Min.	Typ.	Max.		
Storage temperature range	T_stg	-55	-	+125	°C	Satisfy environmental characteristics specifications
Level of drive	DL	-	-	500	μ W	No damage

[3] Operating Conditions

Item	Symbol	Rating value			Unit	Note
		Min.	Typ.	Max.		
Operating temperature range	T_use	-40	-	+125	°C	
Level of drive	DL	0.01	10	200	μ W	Recommended:10 μ W

[4] Static Characteristics

Item	Symbol	Specifications			Unit	Conditions / Remarks
		Min.	Typ.	Max.		
Nominal frequency range	f_nom	24	-	80	MHz	Please contact Epson about available frequencies
		24, 25, 26, 27, 32, 37.4, 38.4, 40, 50, 52, 55.2, 59.97, 76.8, 80				Standard frequency
Frequency tolerance	f_tol	-10	-	+10	$\times 10^{-6}$	+25 °C ± 3 °C DL = 10 μ W Does not include frequency aging
Frequency vs. temperature characteristics	f_tem	$\pm 20 \times 10^{-6}$ / -40 °C to +85 °C			-	Reference at +25 °C ± 3 °C Specify from the list on the left. Please contact us for anything other than those listed on the left.
		$\pm 25 \times 10^{-6}$ / -40 °C to +105 °C				
		$\pm 50 \times 10^{-6}$ / -40 °C to +125 °C				
Motional resistance (ESR)	R1	Table 1.			-	π circuit IEC 60444-2 T_use = Operating temperature range DL = 10 μ W
Shunt capacitance	C0	-	-	1.0	pF	π circuit and Network Analyzer
Load capacitance	CL	6	-	∞	pF	Please specify
Isolation resistance	IR	500	-	-	M Ω	
Frequency aging	f_age	± 3			$\times 10^{-6}$	+25°C, First year *1

*1 The frequency aging shift is an estimate value from reliability test results and is not a guarantee value.

Table 1. Motional resistance (ESR)

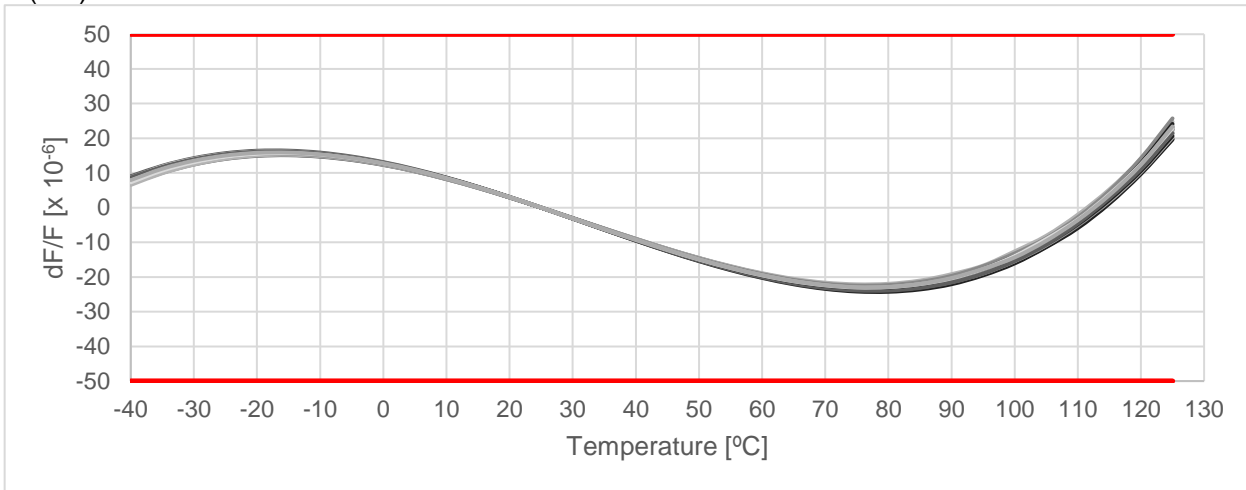
Frequency range	Motional resistance
24 MHz \leq f_nom < 32 MHz	200 Ω Max.
32 MHz \leq f_nom < 52 MHz	80 Ω Max.
52 MHz \leq f_nom \leq 80 MHz	60 Ω Max.

Please contact us for anything other than the above.

[5] Example of Frequency vs. Temperature Characteristics

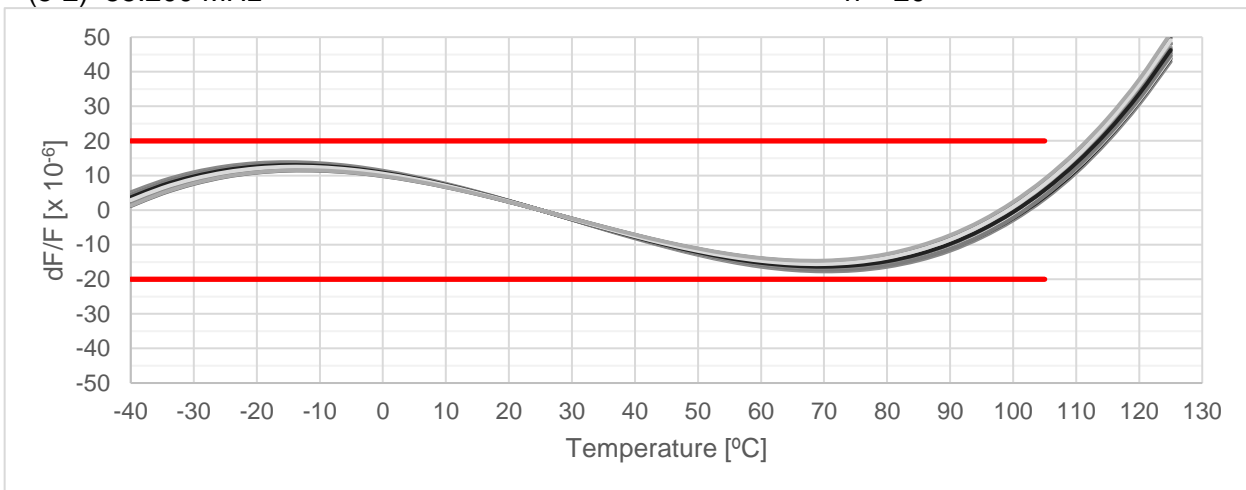
(5-1) 24.000 MHz

n = 20



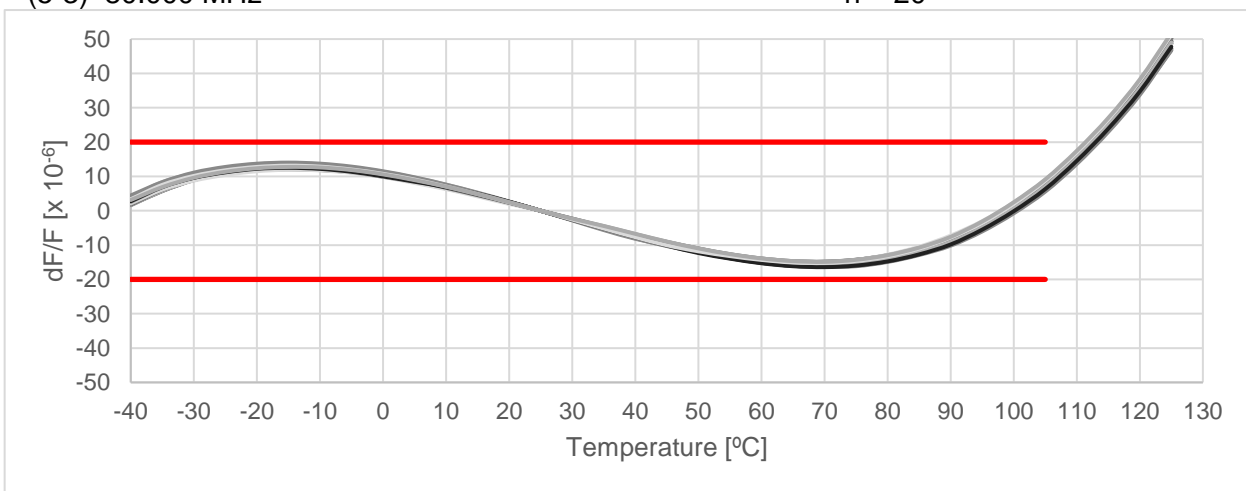
(5-2) 55.200 MHz

n = 20



(5-3) 80.000 MHz

n = 20



[6] Marking Description

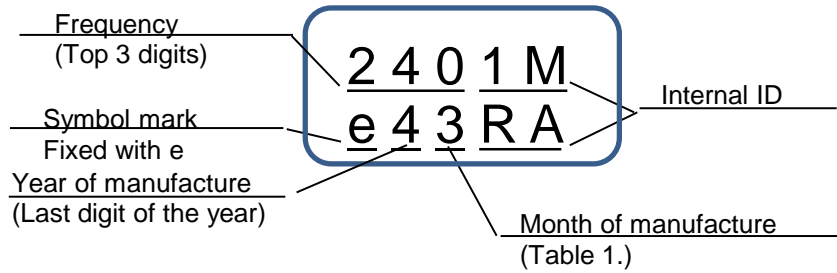
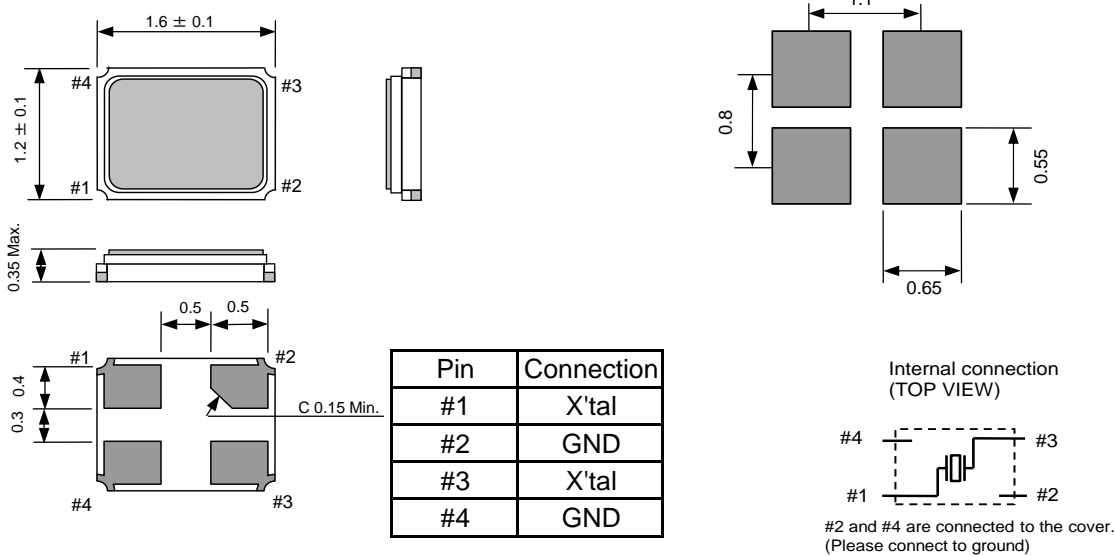


Table 1. Month of manufacture

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	X	Y	Z

[7] Outline Drawing and Recommended Footprint

Unit: mm



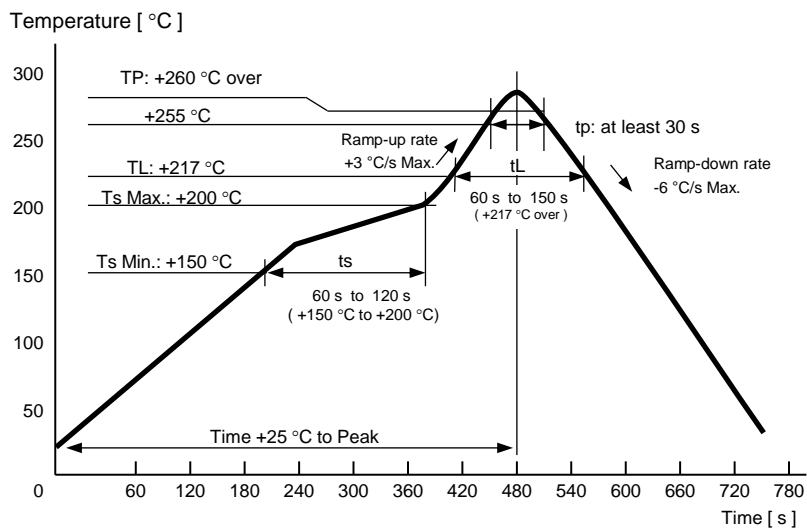
Reference weight Typ.: 3.0 mg

Terminal coating: Au plating

[8] Moisture Sensitivity Level
 (8-1)Moisture Sensitivity Level (MSL)

Parameter	Specification	Conditions
MSL	LEVEL 1	JEDEC J-STD-020E

[9] Reflow Profile
 JEDEC J-STD-020E



[10] Packing Information

(10-1) Packing Quantity

The last two digits of the Product Number (X1E000461xxxx26) defines the packing quantity.
The standard is "26" for a 6 000 pcs/Reel.

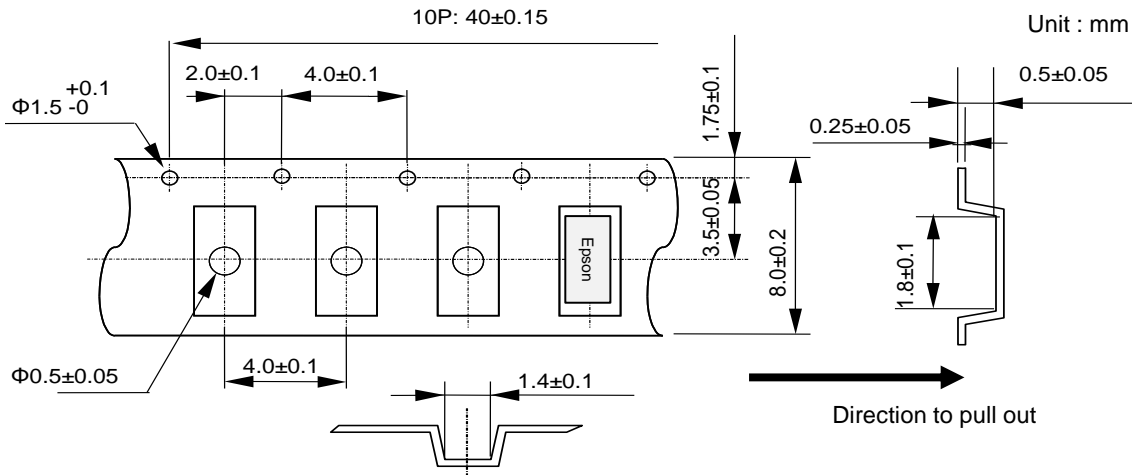
(10-2) Taping Specification

Subject to EIA-481, IEC-60286 and JIS C0806

(1) Tape Dimensions

Carrier Tape Material : PS (Polystyrene)

Top Tape Material : PET (Polyethylene Terephthalate) +PE (Polyethylene)

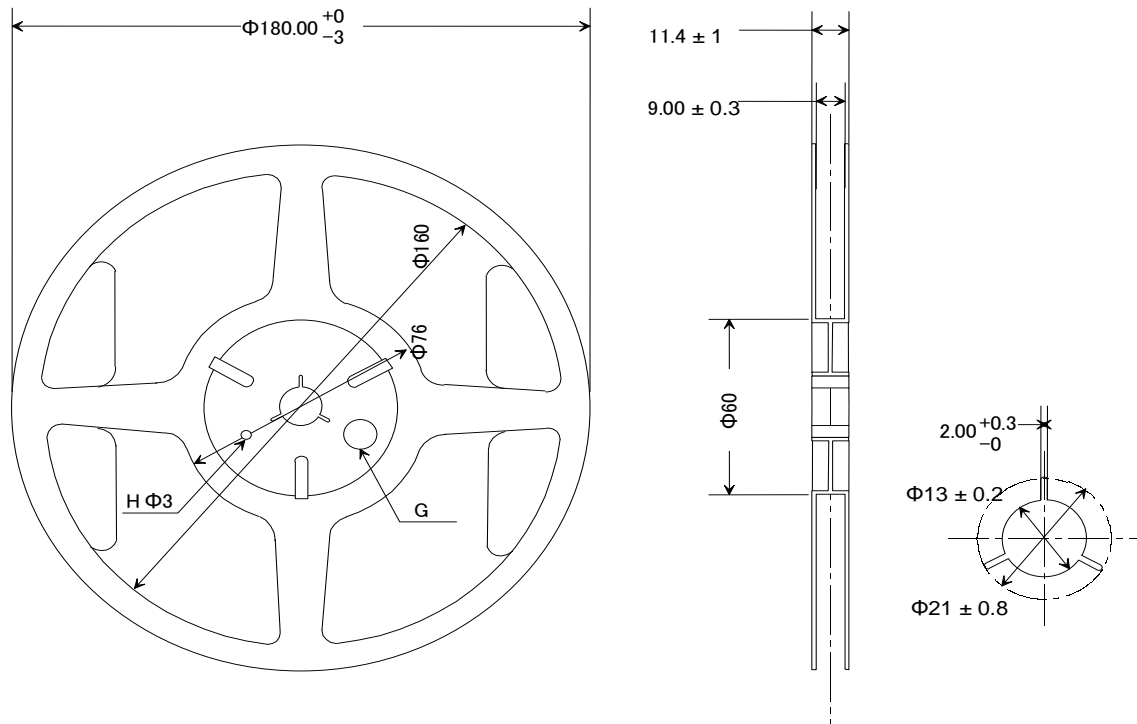


(2) Reel Dimensions

Center Material : PS (Polystyrene)

Reel Material : PS (Polystyrene)

Unit : mm



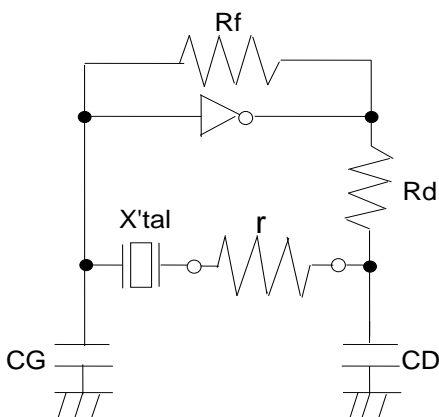
[11] Handling Precautions

Prior to using this product, please carefully read the section entitled “Precautions” on our Web site (<https://www.epsondevice.com/crystal/en/support/precaution/>) for instructions on how to handle and use the product properly to ensure optimal performance of the product in your equipment.

In addition to the foregoing precautions, in order to avoid degrading the performance of the product, we strongly advise that you adhere to the below recommendations:

1. Max 5 times re-flow is allowed. Its recommended to manually solder when not enough/no solder detected.(Using soldering iron at +350 °C × within 5 seconds)
2. Do not expose this product to excessive mechanical shock or vibration.
This product can be damaged by mechanical shock during the soldering process depending on the equipment used, process conditions, and any impact forces experienced.
Always follow appropriate procedures, particularly when changing the assembly process in any way and be sure to follow applicable process qualification standards before starting production.
3. Keep PCB routing from the terminal(s) to the load as short as possible for best performance.
4. Product failures during the warranty period only apply when the product is used according to the recommended operating conditions described in the specifications. Products that have been opened for analysis or damaged will not be covered. It is recommended to store and use in normal temperature and humidity environments described in the specifications to ensure frequency accuracy and prevent moisture condensation. If the product is stored for more than one year, please confirm the pin solderability prior to use.
5. This product may be affected to ultrasonic cleaning. It is depends on the cleaning conditions (Cleaning machine type / power/time / content/position etc.). The warranty will not cover any damage due to this type of usage. Check conditions prior to use.
6. If the oscillation circuit is exposed to condensation, the frequency may change or oscillation may stop.
Do not use in any conditions where condensation occurs.
7. If an excessive excitation is applied to the crystal unit, the characteristics may be degraded or destruction may occur.
Design the oscillation circuit so that the excitation level is appropriate.
8. Depending on the method and conditions used to measure characteristic values such as frequency, deviation from our measured values may occur. Please check and verify the characteristics before use.
9. Do not route any signal lines, supply voltage lines, or GND lines underneath the area where the oscillators are mounted including any internal layers and on the opposite side of the PCB.
To avoid any issues due to interference of other signal lines, please take care not to place signal lines near the product as this may have an adverse affect on the performance of the product.
10. Since this product is thin, please check the thickness and amount of solder paste in advance to ensure that short circuits do not occur.
11. If sufficient negative resistance is not provided by the oscillation circuit, the Xtal may not oscillate or take a long time to start. Please design the circuit as follows.
If there are any recommended conditions from the IC manufacturer, please follow them.
12. Aging specifications are estimated from environmental reliability tests and expected frequency variation over time. They do not provide a guarantee of aging over the product lifecycle.
13. Should any customer use the product in any manner contrary to the precautions and/or advice herein, such use shall be done at the customer's own risk.

< Check of Negative resistance >



- 1) Insert a pure resistance r in series with the X'tal.
- 2) Adjust r and find the maximum r value that starts oscillation.
- 3) Check the value of r in the oscillation state of 2).
Negative resistance of the circuit $|-R| =$
 $r +$ Series resistance value $R1$ of the X'tal
- 4) Negative resistance $|-R|$ guideline:
 $|-R| > R1$ Max. x 5

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.




ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs, Seiko Epson made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired IATF 16949 certification that is requested strongly by major manufacturers as standard.

IATF 16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

■ Explanation of marks used in this datasheet

	•Pb free.
	•Complies with EU RoHS directive. *About the products without the Pb-free mark. Contains Pb in products exempted by EU RoHS directive (Contains Pb in sealing glass, high melting temperature type solder or other)
	•Designed for automotive applications such as Car Multimedia, Body Electronics, Remote Keyless Entry etc.

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